# PUBLICLY AVAILABLE SPECIFICATION



**Pre-Standard** 

First edition 2005-09

Electronic components – Long-duration storage of electronic components – Guidance for implementation

© IEC 2005 — Copyright - all rights reserved

No part of this publication may be reproduced or utilized in any form or by any means, electronic or mechanical, including photocopying and microfilm, without permission in writing from the publisher.

International Electrotechnical Commission, 3, rue de Varembé, PO Box 131, CH-1211 Geneva 20, Switzerland Telephone: +41 22 919 02 11 Telefax: +41 22 919 03 00 E-mail: inmail@iec.ch Web: www.iec.ch



Commission Electrotechnique Internationale International Electrotechnical Commission Международная Электротехническая Комиссия PRICE CODE

For price, see current catalogue

IJ

# CONTENTS

FO	REWO	RD	4					
INT	rodi	CTION	5					
1	Scop		6					
2	Norm	ative references	6					
3	Storage decision criteria							
	3.1	Advantages						
	••••	3.1.1 Technical simplicity – Rapidity	7					
		3.1.2 Solution durability	7					
		3.1.3 Preventive storage	7					
	3.2	Hazards – Drawbacks						
		3.2.1 Generic aging hazard	7					
		3.2.2 Poor stock dimensioning	7					
		3.2.3 Incorrect control of reliability during storage	8					
		3.2.4 Freezing equipment functionalities	8					
	3.3	Storage cost	8					
	3.4	Decision criteria	8					
4	Purc	asing – Procurement	9					
	4.1	List of components	9					
	4.2	Quantity of components to be stored	9					
		4.2.1 Production stock	9					
		4.2.2 Field service stock	9					
	4.3	When is it worth keeping in stock?	10					
	4.4	Procurement recommendations	10					
5	Tech	ical validation of the components	10					
	5.1	Purpose	10					
	5.2	Relevant field	10					
	5.3	Test selection criteria	11					
	5.4	Measurements and tests	11					
		5.4.1 Sampling	11					
		5.4.2 Visual examination, sealing, solderability	11					
		5.4.3 Compliance with the electrical specifications	12					
		5.4.4 Assessment of the supplied batch reliability	13					
		5.4.5 Manufacturing control check (technological analysis)	15					
~	5.5	Sanction	15					
6	Conc	nditioning and storage						
	6.1	Type of environment						
	6.2	Elementary storage unit						
	6.3	Slock management						
	6.4 0.5	4 Redundancy						
	6.5	luentincation – Fraceability1						
	0.0 6.7	Stabilization baka						
	0./	Stavinzaliun väke	17					
	0.0	Slorage conditions	17					
		6.8.2 Temperature	17					
			17					

		6.8.3	Temperature variations	17				
		6.8.4	Relative humidity – Chemical attacks – Contamination	17				
		6.8.5	Pressure	17				
		6.8.6	Electrostatic discharges	17				
		6.8.7	Vibration – Mechanical impacts	18				
		6.8.8	Electromagnetic field – Radiation	18				
		6.8.9	Light	18				
	6.9	Maintai	ning storage conditions	18				
7	Perio	dic cheo	ck of the components	18				
	7.1	Objecti	ves	18				
	7.2	Periodi	city	19				
	7.3	Tests d	luring periodic check	19				
8	Desto	ocking		19				
	8.1	Precau	tions	19				
		8.1.1	Electrostatic discharges	19				
		8.1.2	Mechanical impacts.	19				
	8.2	Inspect	.ion	19				
9	Feed	back		20				
Anr	nex A	(informa	tive) Example of a component list	21				
Anr	iex B	(informa	tive) Examples of periodic and/or destocking tests (1/3)	23				
Anr	iex C	(informa	tive) Parameters influencing the final price of the component storage	25				
Anr	iex D	(informa	tive) Parameters influencing the quantity of components to be stored	26				
Annex E (normative) Failure mechanisms: Encansulated and non-encansulated active								
	comp	onents.		27				
Anr	nex F (	normati	ve) Failure mechanisms: GaAs components	29				
	·		,					

## INTERNATIONAL ELECTROTECHNICAL COMMISSION

## **ELECTRONIC COMPONENTS -**

## Long-duration storage of electronic components – Guidance for implementation

## FOREWORD

- 1) The International Electrotechnical Commission (IEC) is a worldwide organization for standardization comprising all national electrotechnical committees (IEC National Committees). The object of IEC is to promote international co-operation on all questions concerning standardization in the electrical and electronic fields. To this end and in addition to other activities, IEC publishes International Standards, Technical Specifications, Technical Reports, Publicly Available Specifications (PAS) and Guides (hereafter referred to as "IEC Publication(s)"). Their preparation is entrusted to technical committees; any IEC National Committee interested in the subject dealt with may participate in this preparatory work. International, governmental and non-governmental organizations for Standardization (ISO) in accordance with conditions determined by agreement between the two organizations.
- 2) The formal decisions or agreements of IEC on technical matters express, as nearly as possible, an international consensus of opinion on the relevant subjects since each technical committee has representation from all interested IEC National Committees.
- 3) IEC Publications have the form of recommendations for international use and are accepted by IEC National Committees in that sense. While all reasonable efforts are made to ensure that the technical content of IEC Publications is accurate, IEC cannot be held responsible for the way in which they are used or for any misinterpretation by any end user.
- 4) In order to promote international uniformity, IEC National Committees undertake to apply IEC Publications transparently to the maximum extent possible in their national and regional publications. Any divergence between any IEC Publication and the corresponding national or regional publication shall be clearly indicated in the latter.
- 5) IEC provides no marking procedure to indicate its approval and cannot be rendered responsible for any equipment declared to be in conformity with an IEC Publication.
- 6) All users should ensure that they have the latest edition of this publication.
- 7) No liability shall attach to IEC or its directors, employees, servants or agents including individual experts and members of its technical committees and IEC National Committees for any personal injury, property damage or other damage of any nature whatsoever, whether direct or indirect, or for costs (including legal fees) and expenses arising out of the publication, use of, or reliance upon, this IEC Publication or any other IEC Publications.
- 8) Attention is drawn to the Normative references cited in this publication. Use of the referenced publications is indispensable for the correct application of this publication.
- 9) Attention is drawn to the possibility that some of the elements of this IEC Publication may be the subject of patent rights. IEC shall not be held responsible for identifying any or all such patent rights.

A PAS is a technical specification not fulfilling the requirements for a standard but made available to the public.

IEC-PAS 62435 has been processed by IEC technical committee 47: Semiconductor devices.

The text of this PAS is based on the following document:	This PAS was approved for publication by the P-members of the committee concerned as indicated in the following document

Draft PAS	Report on voting
47/1792/NP	47/1826/RVN

Following publication of this PAS, which is a pre-standard publication, the technical committee or subcommittee concerned will transform it into an International Standard.

This PAS shall remain valid for an initial maximum period of three years starting from 2005-09. The validity may be extended for a single three-year period, following which it shall be revised to become another type of normative document or shall be withdrawn.

#### INTRODUCTION

This PAS applies to the long-duration storage of electronic components.

Although it has always existed to some extent, obsolescence of electronic components and particularly of integrated circuits, has become increasingly intense over the last few years.

Indeed, with the existing technological boom, the commercial life of a component has become very short compared with the life of industrial equipment such as that encountered in the aeronautical field, the railway industry or the energy sector.

The many solutions enabling obsolescence to be resolved are now identified. However, selecting one of these solutions must be preceded by a case-by-case technical and economic feasibility study, depending on whether storage is envisaged for field service or production, for example:

- remedial storage as soon as components are no longer marketed;
- preventive storage anticipating declaration of obsolescence.

Taking into account the expected life of some installations, sometimes covering several decades, the qualification times, and the unavailability costs, which can also be very high, the solution to be adopted to resolve obsolescence must often be rapidly implemented. This is why the solution retained in most cases consists in systematically storing components which are in the process of becoming obsolescent.

The technical risks of this solution are, *a priori*, fairly low. However, it requires perfect mastery of the implemented process and especially of the storage environment, although this mastery becomes critical when it comes to long-term storage.

All handling, protection, storage and test operations must be performed according to the state of the art.

The application of the approach proposed in this document in no way guarantees that the stored components are in perfect operating condition at the end of this storage. It only comprises a means of minimizing potential and probable degradation factors.

## **ELECTRONIC COMPONENTS –**

## Long-duration storage of electronic components – Guidance for implementation

#### 1 Scope

This Publicly Available Specification (PAS) is, first of all, a practical guide to methods of longduration storage (more than five years) which summarizes the existing practices in the industry.

Unless otherwise specified, the approach, as well as the methods presented, apply to all families of electronic components, such as

- passive components, including quartz crystals, connectors and relays. However, components with "manufacturer's" specifications showing an expiry date or specific storage conditions are excluded from this document (for example, primary cells, storage cells, etc.);
- encapsulated or non-encapsulated active components of a silicon [Si] or gallium arsenide [GaAs] technology;
- micro-electronic assemblies.

### 2 Normative references

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60068-2-17:1994, Basic environmental test procedures – Part 2: Tests – Test Q: Sealing

IEC 60068-2-20:1979, Environmental testing – Part 2: Tests – Test T: Soldering

IEC 60410:1973, Sampling plans and procedures for inspection by attributes

IEC 61340-5-1:1998, *Electrostatics – Part 5-1: Protection of electronic devices from electrostatic phenomena – General requirements* 

IEC 61340-5-2:1999, *Electrostatics – Part 5-2: Protection of electronic devices from electrostatic phenomena – User guide* 

IEC 61945, Integrated circuits – Manufacturing line approval – Methodology for technology and failure analysis

IEC 62380: Reliability data handbook – Universal model for reliability prediction of electronics components, PCBs and equipment

EN 190 000:1995, Generic specification – Integrated monolithic circuits